

2.7x3.5mm SURFACE MOUNT LED LAMP

Part Number: KA-2735SURKCGKS

Hyper Red Green

Features

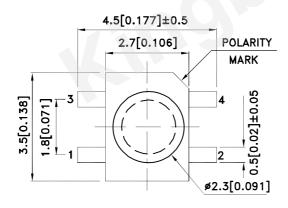
- 2.7mm X 3.5mm SMT LED, 1.5mm height only.
- Both chips can be controlled separately.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package: 1000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

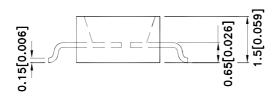
Description

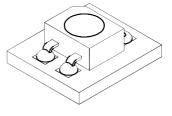
The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions







- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAM1391 **APPROVED: WYNEC**

REV NO: V.2A CHECKED: Allen Liu **DATE: MAR/28/2013** DRAWN: Y.Liu



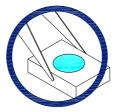
PAGE: 1 OF 7 ERP: 1201008132

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

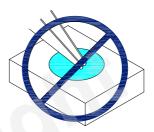
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

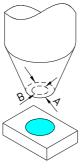




Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Detailed application notes are listed on our website.

http://www.kingbright.com/application_notes

SPEC NO: DSAM1391 REV NO: V.2A DATE: MAR/28/2013 PAGE: 2 OF 7

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008132

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KA-2735SURKCGKS	Hyper Red (AlGaInP)	- Water Clear	120	300	- 120°
			*50	*100	
	Green (AlGaInP)		40	65	
			*40	*65	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.
 *Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	645 574		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	IF=20mA
С	Capacitance	Hyper Red Green	35 15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	IF=20mA
VF [2]	Forward Voltage	Hyper Red Green		10 10	uA	VR=5V

Notes:

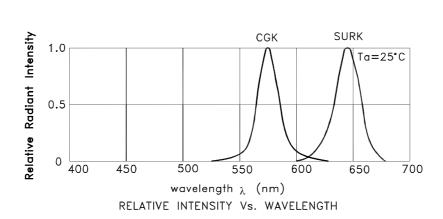
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

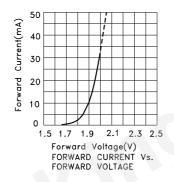
Parameter	Hyper Red	Green	Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	185	150	mA		
Reverse Voltage		V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

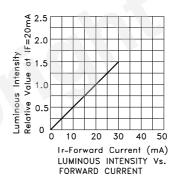
Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

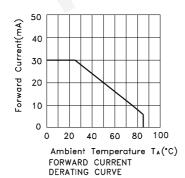
SPEC NO: DSAM1391 **REV NO: V.2A** DATE: MAR/28/2013 PAGE: 3 OF 7 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201008132

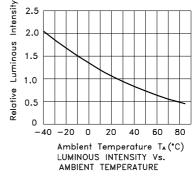


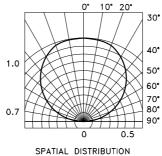
KA-2735SURKCGKS Hyper Red







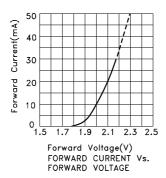


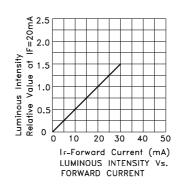


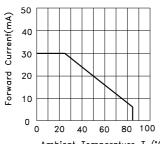
SPEC NO: DSAM1391 REV NO: V.2A DATE: MAR/28/2013 PAGE: 4 OF 7

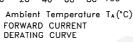
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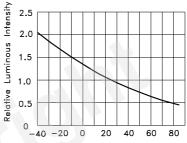
Green



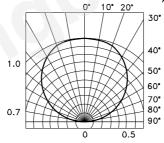








Ambient Temperature TA (°C) LUMINOUS INTENSITY Vs. AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

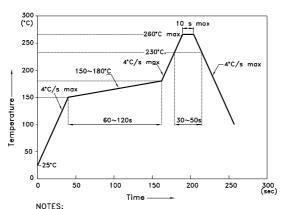
SPEC NO: DSAM1391 REV NO: V.2A DATE: MAR/28/2013 PAGE: 5 OF 7

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008132

KA-2735SURKCGKS

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



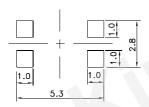
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

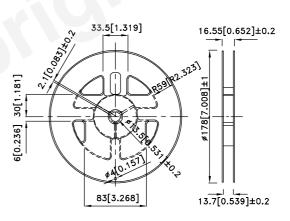
 3.Number of reflow process shall be 2 times or less.

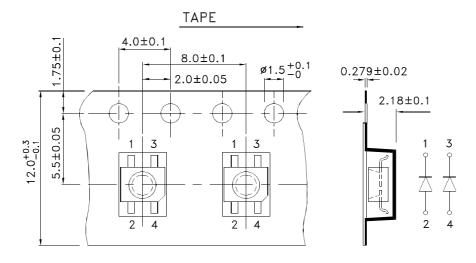
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



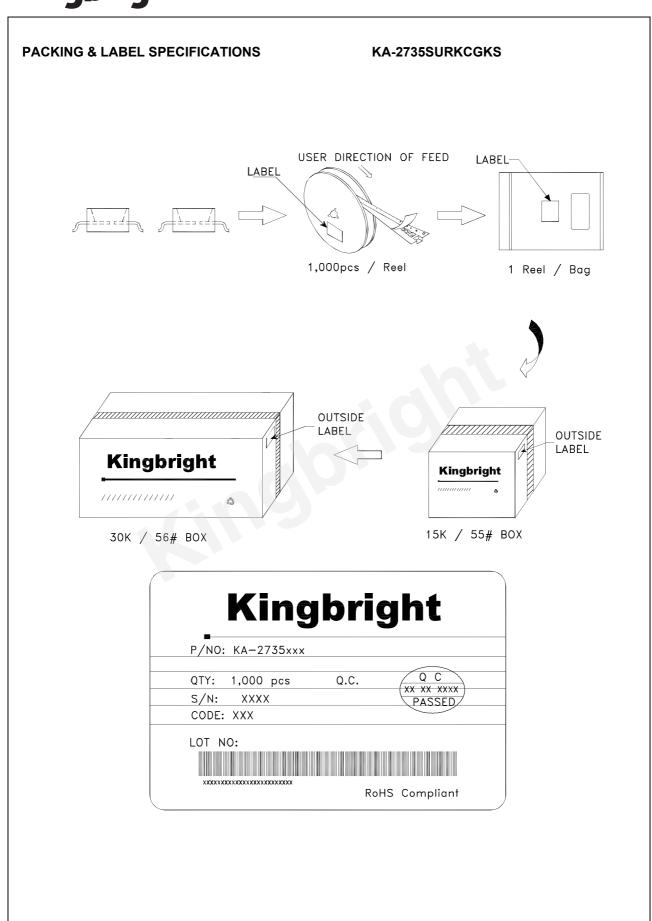
Tape Dimensions (Units : mm)

Reel Dimension





SPEC NO: DSAM1391 **REV NO: V.2A DATE: MAR/28/2013** PAGE: 6 OF 7 **APPROVED: WYNEC CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201008132



SPEC NO: DSAM1391 APPROVED: WYNEC REV NO: V.2A CHECKED: Allen Liu DATE: MAR/28/2013 DRAWN: Y.Liu PAGE: 7 OF 7 ERP: 1201008132